

Thin film soldered SAM on W/Cu submount, glued with silver epoxy on a water cooled copper heat sink with 25.0 mm diameter for high power applications

SAM- λ -A-25.0h

SAM chip area	standard:	4mm x 4mm
Chip thickness	standard:	400 μ m
Front side	the SAM is protected with a dielectric front layer	

The SAM chip is thin film soldered on a gold plated W/Cu submount using a Au/Sn solder.

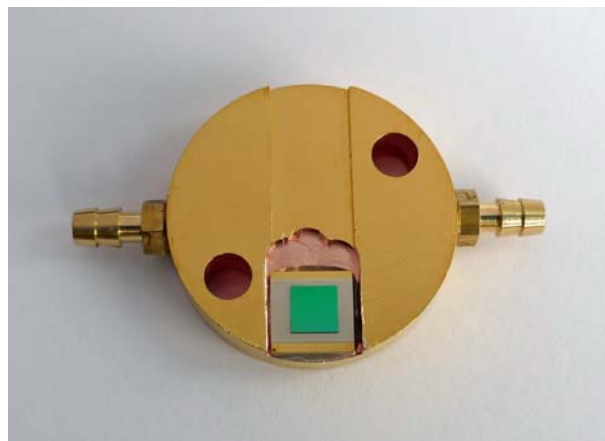
Submount dimensions: 7mm x 7mm x 1mm

Submount material: W/Cu 90 / 10

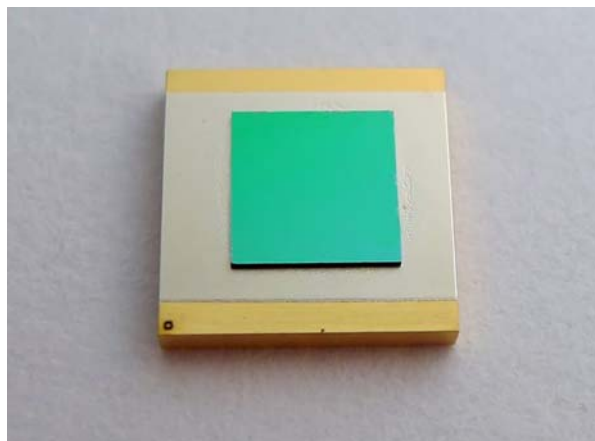
The W/Cu submount is glued using a silver containing epoxy on a water cooled copper heat sink with 25.0 mm diameter. This heat sink combination ensures a low temperature of the absorber layer in case of high dissipated power ≥ 1 W.

- The **standard** position of the SAM is at the center of the water cooled heat sink.
- **Optional** the SAM can be mounted on the edge of the water cooled heat sink without extra charges.

Edge mounted SAM



SAM on W/Cu submount



Cu/W submount